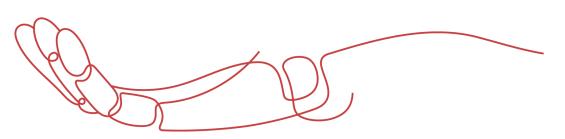


# **PRODUCT DATA SHEET**



To learn more about JGSEMI, please visit our website at







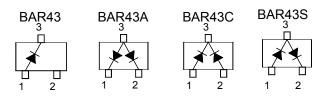
Datasheet

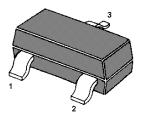
Samples

Please note: Please check the JINGAO Semiconductor website to verify the updated device numbers. The most current and up-to-date ordering information can be found at www.jg-semi.cn. Please email any questions regarding the system integration to JINGAO\_questions@jgsemi.com.



SCHOTTKY BARRIER DIODE





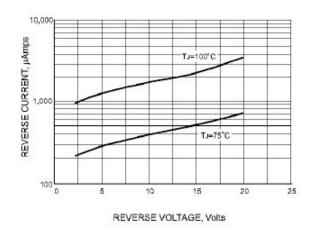
**SOT-23** 

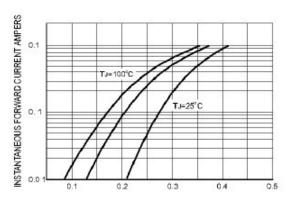
## Absolute Maximum Ratings (T<sub>a</sub> = 25 °C)

Parameter	Symbol	Value	Unit
Maximum Repetitive Reverse Voltage	$V_{RRM}$	30	V
Average Rectified Forward Current	I <sub>F(AV)</sub>	200	mA
Non-repetitive Peak Forward Surge Current at (t = 1 s)	I <sub>FSM</sub>	750	mA
Power Dissipation	P <sub>tot</sub>	290	mW
Thermal Resistance, Junction to Ambient	$R_{ heta JA}$	430	°C/W
Operating Junction Temperature	T <sub>J</sub>	150	°C
Storage Temperature Range	T <sub>S</sub>	- 55 to + 150	°C

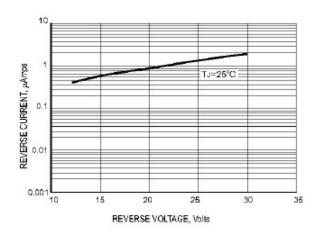
### Characteristics at T<sub>a</sub> = 25 °C

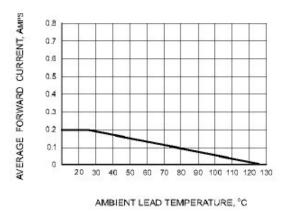
Parameter	Symbol	Min.	Max.	Unit
Reverse Breakdown Voltage at I <sub>R</sub> = 100 μA	$V_{(BR)R}$	30	-	V
Reverse Current at V <sub>R</sub> = 25 V	I <sub>R</sub>	-	500	nA
Forward Voltage at $I_F = 2 \text{ mA}$ at $I_F = 15 \text{ mA}$ at $I_F = 100 \text{ mA}$	V <sub>F</sub>	0.26 - -	0.33 0.45 0.8	V
Reverse Recovery Time at $I_F = I_R = 10$ mA, $I_{RR} = 1$ mA, $I_{RR} = 100$ $I_{RR} = 100$	t <sub>rr</sub>	-	5	ns





INSTANTANEOUS FORWARD VOLTAGE, VOLTS



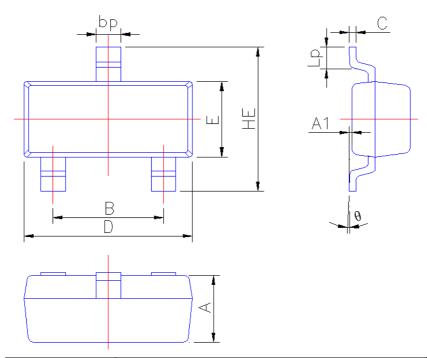




#### **PACKAGE OUTLINE**

Plastic surface mounted package; 3 leads

**SOT-23** 



Cymbol	Dimension in Millimeters		
Symbol	Min	Max	
А	0.90	1.10	
A1	0.013	0.100	
В	1.80	2.00	
bp	0.35	0.50	
С	0.09	0.150	
D	2.80	3.00	
Е	1.20	1.40	
HE	2.20	2.80	
Lp	0.20	0.50	
θ	0°	5°	



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